

- N.B:** (1) Question No.1 is Compulsory.  
 (2) Attempt any Four out of remaining six questions.  
 (3) Assume suitable data wherever necessary

1. Attempt any four :

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- (a) Compare ion implantation and diffusion.  
 (b) Draw VTC of three CMOS inverter with  $K_R = 1$ ,  $K_R < 1$  &  $K_R > 1$ .  
 (c) Two n-MOS transistors (M1 & M2) connected in series shown in fig find output voltage for  
 i)  $V_a = 2.7V$ , ii)  $V_a = 3V$ .  
 $V_{TH} = 0.7V$



- (d) Explain MOSFET works as a capacitor. 10

2. (a) Explain operation of CMOS inverter with clearly mentioning the five cases given below. 10

- (i)  $V_{in} < V_{TO,n}$   
 (ii)  $V_{in} = V_{IL}$   
 (iii)  $V_{in} = V_{IH}$   
 (iv)  $V_{in} > V_{DD} + V_{TO,p}$   
 (v)  $V_{in} = V_{TH}$

(b) Draw the p-well CMOS inverter and explain the latch up effect in it. What are remedies to avoid latch up problem. 10

3. (a) Calculate threshold voltage  $V_{TO}$  at  $V_{SB} = 0$  for a polysilicon gate n-channel MOS transistor with following parameters. 10

$$N_A = 10^{16} \text{ cm}^{-3}, \quad N_D = 2 \times 10^{20} \text{ cm}^{-3}$$

$$t_{ox} = 200 \text{ \AA}, \quad N_{SS} = 5 \times 10^{11} \text{ cm}^{-2}$$

(b) Write a verilog code for  $4 \times 4$  barrel shifter. 10

4. (a) Draw a circuit diagram, stick diagram and layout for following equation 10  
 $Y = A \cdot B \cdot C$   
 Use CMOS technology.
- (b) Consider a CMOS inverter circuit with the following parameters 10  
 $V_{DD} = 3.3V$   $V_{TO,n} = 0.6V$   $V_{TO,p} = -0.7V$   
 $\mu_n C_{ox} = 60 \mu A/V^2, (W/L)_n = 8$   
 $\mu_p C_{ox} = 20 \mu A/V^2, (W/L)_p = 12$   
 Calculate the noise margin.
5. (a) Describe the hot electron and short channel effect in MOS device. Also 10  
 explain their effect on MOS characteristic.
- (b) Explain necessity of design rules ? Explain  $\lambda$  based design rules in detail. 10
6. (a) Define scaling. Explain constant voltage and constant field scaling in detail. 10  
 (b) Explain the method to design 4:1 MUX using NMOS pass transistor logic. 10  
 Draw complete stick diagram.
7. Write a short notes on (any three) : 20  
 (i) MOS CV characteristics  
 (ii) VLSI design flow  
 (iii) Semicustom and full custom design  
 (iv) Transistor sizing.